May 2001

## **FDS9953A** Dual 30V P-Channel PowerTrench<sup>®</sup> MOSFET

#### **General Description**

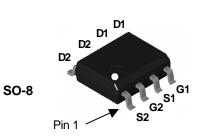
This P.Channel MOSFET is a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications requiring a wide range of gave drive voltage ratings (4.5V - 25V).

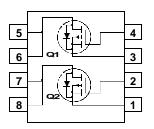
#### Applications

- Power management
- Load switch
- Battery protection

#### Features

- -2.9 A, -30 V  $R_{DS(ON)} = 130 \text{ m}\Omega @ V_{GS} = -10 \text{ V}$  $R_{DS(ON)} = 200 \text{ m}\Omega @ V_{GS} = -4.5 \text{ V}$
- Low gate charge (2.5nC typical)
- Fast switching speed
- + High performance trench technology for extremely low  $R_{\text{DS}(\text{ON})}$
- High power and current handling capability





### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V <sub>DSS</sub>	Drain-Source	Voltage	-30	V	
V <sub>GSS</sub>	Gate-Source Voltage			±25	
l <sub>D</sub>	Drain Current	t – Continuous	(Note 1a)	±2.9	Α
		– Pulsed		±10	
P₀	Power Dissipation for Dual Operation			2	W
	Power Dissipation for Single Operation		(Note 1a)	1.6	
			(Note 1b)	1	
			(Note 1c)	0.9	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		erature Range	-55 to +150	
Therma	I Characte	eristics			
$R_{\theta JA}$	Thermal Res	Thermal Resistance, Junction-to-Ambient (Note 1a)		78	
R <sub>0JC</sub>	Thermal Resistance, Junction-to-Case (Note 1)		(Note 1)	40 °	
Packag	e Marking	and Ordering In	formation		· · · ·
Device Marking		Device	Reel Size	Tape width	Quantity
FDS9953A		FDS9953A	13"	12mm	2500 units

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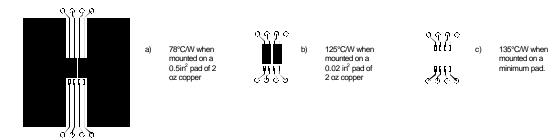
FDS9953A

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BV <sub>DSS</sub>	Drain–Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	-30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C		-23		mV/°C
	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -24 \text{ V}, \qquad V_{\text{GS}} = 0 \text{ V}$			-2	μA
GSSF	Gate-Body Leakage, Forward	$V_{GS} = -25 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			-100	nA
GSSR	Gate-Body Leakage, Reverse	$V_{GS} = 25 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
On Char	acteristics (Note 2)		I			
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	-1	-1.8	-3.0	V
$\Delta V_{GS(th)} \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$l_D = -250 \ \mu\text{A}$ , Referenced to 25°C		4		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance			95 137 142 202	130 200 200 310	mΩ
	On–State Drain Current		-5			Α
D(on)		$V_{GS} = -4.5 \text{ V},  V_{DS} = -5 \text{ V}$	-1.5			
<b>g</b> fs	Forward Transconductance	$V_{DS} = -15 V$ , $I_D = -1 A$		4		S
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -15 V$ , $V_{GS} = 0 V$ ,		185		pF
Coss	Output Capacitance			56		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1.0 MHz		26		pF
Switchin	g Characteristics (Note 2)					
t <sub>d(on)</sub>	Turn–On Delay Time	$V_{DD} = -15 V$ , $I_D = -1 A$ ,		4.5	9	ns
t <sub>r</sub>	Turn–On Rise Time	$V_{GS} = -10 \text{ V}, \qquad R_{GEN} = 6 \ \Omega$		13	23	ns
t <sub>d(off)</sub>	Turn–Off Delay Time			11	20	ns
t <sub>f</sub>	Turn–Off Fall Time			2	4	ns
Qg	Total Gate Charge	$V_{DS} = -5 V$ , $I_D = -1 A$ ,		2.5	3.5	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{GS} = -10 V$		0.8		nC
Q <sub>gd</sub>	Gate-Drain Charge			0.9		nC
Drain-So	ource Diode Characteristics	and Maximum Ratings				
ls	Maximum Continuous Drain-Source	-			-1.2	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 V, I_S = -1.3 A$ (Note 2)		-0.8	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, l⊧ = −1.25A, dl⊧/dt = 100A/µs		17	100	nS

### **Typical Characteristics**

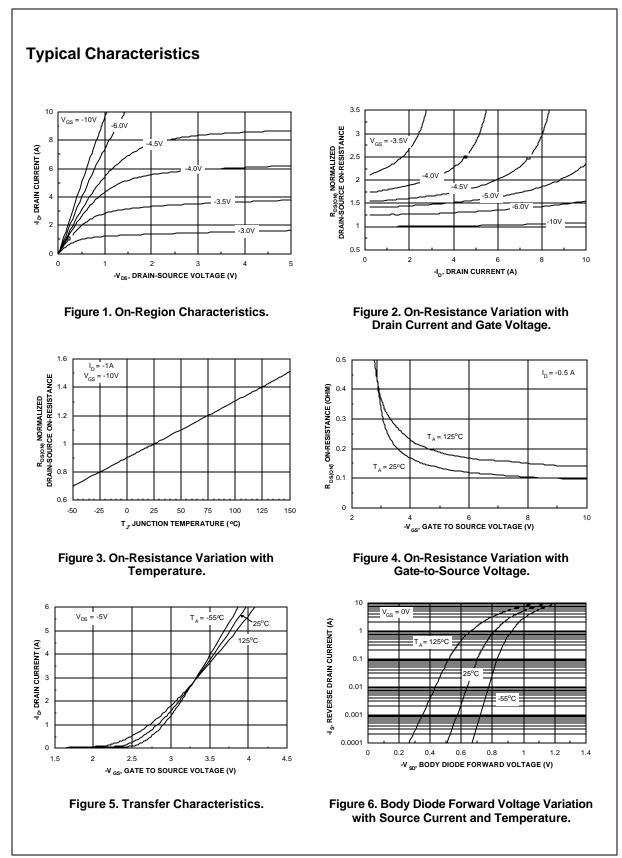
Notes:

 R<sub>RUR</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>RUC</sub> is guaranteed by design while R<sub>RCA</sub> is determined by the user's board design.

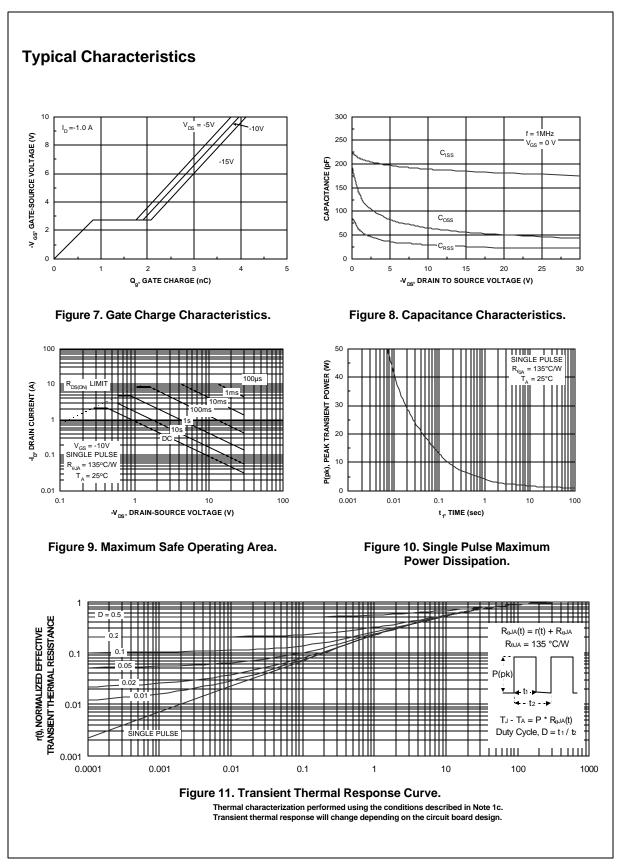


Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%



# FDS9953A



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FDS9953A Rev B(W)

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